# Product Preview

# 20 V, 5 A, Low V<sub>CE(sat)</sub> PNP Transistor

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

# **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-20	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-30	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-6.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-3.0	Adc
Collector Current – Peak	I <sub>CM</sub>	-5.0	Α
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 1)	TBD	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	TBD	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	TBD	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	TBD	°C/W
Thermal Resistance, Junction-to-Lead #1	$R_{ heta JL}$	TBD	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 2)	TBD	W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 X 1.0 inch Pad

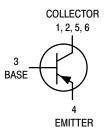
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# ON Semiconductor

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# $\begin{array}{c} \text{20 VOLTS} \\ \text{5.0 AMPS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 78 m} \Omega \end{array}$





CASE 318G TSOP STYLE 6

# **DEVICE MARKING**



VS1= Specific Device Code

d = Date Code

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS20300MR6T1G	TSOP-6 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

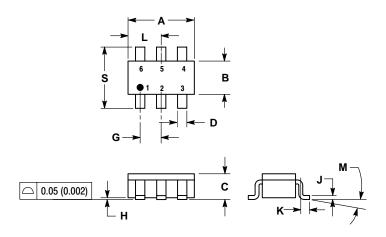
# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typical	Max	Unit
OFF CHARACTERISTICS	<u>.</u>				
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-20		_	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-30		_	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	-6.0		_	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -20 Vdc, I <sub>E</sub> = 0)	Ісво	_		-0.1	μAdc
Collector–Emitter Cutoff Current (V <sub>CES</sub> = -20 Vdc)	ICES	_		-0.1	μAdc
Emitter Cutoff Current $(V_{EB} = -6.0 \text{ Vdc})$	I <sub>EBO</sub>	_		-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain $^{(1)}$ ( $I_C = -1.0 \text{ A}, V_{CE} = -1.5 \text{ V}$ ) ( $I_C = -1.5 \text{ A}, V_{CE} = -2.0 \text{ V}$ ) ( $I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ )	h <sub>FE</sub>	100 100 100		- 400 -	
Collector – Emitter Saturation Voltage (Note 3) ( $I_C = -0.10 \text{ A}, I_B = -0.010 \text{ A}$ ) ( $I_C = -1.0 \text{ A}, I_B = -0.010 \text{ A}$ ) ( $I_C = -2.0 \text{ A}, I_B = -0.02 \text{ A}$ )	V <sub>CE(sat)</sub>	- - -	- - -	-0.015 -0.145 -0.320	V
Base – Emitter Saturation Voltage (Note 3) (I <sub>C</sub> = –1A, I <sub>B</sub> = –0.010 A)	V <sub>BE(sat)</sub>	_	-	-0.85	V
Base – Emitter Turn–on Voltage (Note 3) (I <sub>C</sub> = -2.0 A, V <sub>CE</sub> = -3.0 V)	V <sub>BE(on)</sub>	_	-	-0.875	V
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	-	_	MHz
Input Capacitance (V <sub>EB</sub> = -0.5 V, f = 1.0 MHz)	Cibo	_		650	pF
Output Capacitance (V <sub>CB</sub> = -3.0 V, f = 1.0 MHz)	Cobo	_		100	pF

<sup>3.</sup> Pulsed Condition: Pulse Width ≤ 300 µsec, Duty Cycle ≤ 2%

## **PACKAGE DIMENSIONS**

TSOP-6 CASE 318G-02 **ISSUE N** 



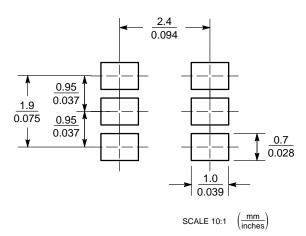
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIA
- OF BASE MATERIAL.
  DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0	10	0	10
S	2.50	3.00	0.0985	0.1181

STYLE 6:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER

- 5. COLLECTOR 6. COLLECTOR

# **SOLDERING FOOTPRINT\***



<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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